

### FEATURES

- Low offset voltage: 100  $\mu\text{V}$  maximum at  $V_S = 5\text{ V}$
- Low input bias current: 1 pA maximum
- Single-supply operation: 5 V to 16 V
- Low noise: 10 nV/ $\sqrt{\text{Hz}}$
- Wide bandwidth: 4 MHz
- Unity-gain stable
- Small package options
  - 3 mm  $\times$  3 mm 8-lead LFCSP
  - 8-lead MSOP and narrow SOIC
  - 14-lead TSSOP and narrow SOIC

### APPLICATIONS

- Sensors
- Medical equipment
- Consumer audio
- Photodiode amplification
- ADC drivers

### GENERAL DESCRIPTION

The AD8661/AD8662/AD8664<sup>1</sup> are rail-to-rail output, single-supply amplifiers that use the Analog Devices, Inc., patented DigiTrim<sup>®</sup> trimming technique to achieve low offset voltage. The AD8661/AD8662/AD8664 series features extended operating ranges, with supply voltages up to 16 V. It also features low input bias current, wide signal bandwidth, and low input voltage and current noise.

The combination of low offset, very low input bias current, and a wide supply range makes these amplifiers useful in a wide variety of applications usually associated with higher priced JFET amplifiers. Systems using high impedance sensors, such as photodiodes, benefit from the combination of low input bias current, low noise, low offset, and wide bandwidth. The wide operating voltage range meets the demands of high performance analog-to-digital converters (ADCs) and digital-to-analog

<sup>1</sup> Protected by U.S. Patents 6,194,962 and 6,696,894.

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### PIN CONFIGURATIONS

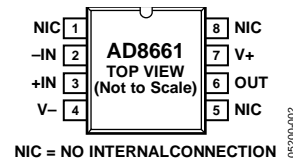


Figure 1. AD8661, 8-Lead SOIC (R-8)

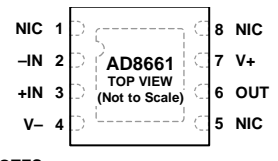


Figure 2. AD8661, 8-Lead LFCSP (CP-8-13)

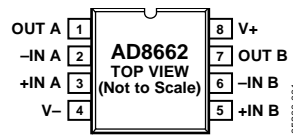


Figure 3. AD8662, 8-Lead SOIC (R-8)

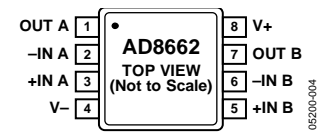


Figure 4. AD8662, 8-Lead MSOP (RM-8)

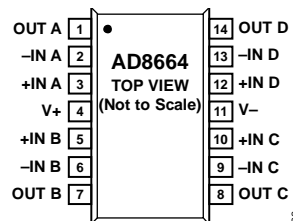


Figure 5. AD8664, 14-Lead SOIC (R-14)

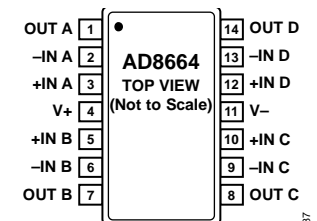


Figure 6. AD8664, 14-Lead TSSOP (RU-14)

converters (DACs). Audio applications and medical monitoring equipment can take advantage of the high input impedance, low voltage, low current noise, and wide bandwidth.

The single AD8661 is available in a narrow 8-lead SOIC package and a very thin, dual lead, 8-lead LFCSP. The AD8661 SOIC package is specified over the extended industrial temperature range of  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . The AD8661 LFCSP is specified over the industrial temperature range of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ . The AD8662 is available in a narrow 8-lead SOIC package and an 8-lead MSOP, both specified over the extended industrial temperature range of  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . The AD8664 is available in a narrow 14-lead SOIC package and a 14-lead TSSOP, both with an extended industrial temperature range of  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .

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<b>REVISION HISTORY</b>			
<b>7/2016—Rev. D to Rev. E</b>			
Changed CP-8-2 to CP-8-13 .....	Throughout	<b>3/2006—Rev. A to Rev. B</b>	
Changes to Figure 1 and Figure 2.....	1	Added AD8662 .....	Universal
Added Patent Note, Note 1.....	1	Added MSOP .....	Universal
Updated Outline Dimensions .....	13	Changes to Table 1.....	3
Changes to Ordering Guide .....	15	Changes to Table 2.....	4
		Changes to Table 3.....	5
		Changes to Table 4.....	6
		Changes to Table 5.....	7
		Updated Outline Dimensions .....	13
		Changes to Ordering Guide .....	13
<b>7/2006—Rev. C to Rev. D</b>			
Added AD8664 .....	Universal	<b>1/2006—Rev. 0 to Rev. A</b>	
Added 14-Lead SOIC_N and 14-Lead TSSOP .....	Universal	Added LFCSP_VD .....	Universal
Changes to Features.....	1	Changes to Table 1.....	3
Changes to Table 1.....	3	Changes to Table 2.....	4
Changes to Table 2.....	4	Changes to Ordering Guide .....	13
Changes to Table 3.....	5		
Changes to Table 4.....	6	<b>9/2005—Revision 0: Initial Version</b>	
Changes to Table 5 and Table 6.....	7		
Changes to Figure 29.....	11		
Updated Outline Dimensions .....	13		
Changes to Ordering Guide .....	15		
<b>5/2006—Rev. B to Rev. C</b>			
Changes to Ordering Guide .....	13		

## SPECIFICATIONS

## AD8661/AD8662/AD8664 ELECTRICAL CHARACTERISTICS—SOIC, MSOP, AND TSSOP

$V_S = 5.0\text{ V}$ ,  $V_{CM} = V_S/2$ ,  $T_A = 25^\circ\text{C}$ , unless otherwise noted.

Table 1.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
<b>INPUT CHARACTERISTICS</b>						
Offset Voltage	$V_{OS}$	$V_{CM} = V_S/2$		30	100	$\mu\text{V}$
AD8661		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			1000	$\mu\text{V}$
AD8661		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			1400	$\mu\text{V}$
AD8662		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			1000	$\mu\text{V}$
AD8664		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			1200	$\mu\text{V}$
Input Bias Current	$I_B$			0.3	1	$\text{pA}$
		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			50	$\text{pA}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			300	$\text{pA}$
Input Offset Current	$I_{OS}$			0.2	0.5	$\text{pA}$
		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			20	$\text{pA}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			75	$\text{pA}$
Input Voltage Range			-0.1		+3.0	$\text{V}$
Common-Mode Rejection Ratio	CMRR	$V_{CM} = -0.1\text{ V to }+3.0\text{ V}$	85	100		$\text{dB}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$	80	100		$\text{dB}$
Large Signal Voltage Gain	$A_{VO}$	$R_L = 2\text{ k}\Omega$ , $V_O = 0.5\text{ V to }4.5\text{ V}$	100	220		$\text{V/mV}$
Offset Voltage Drift	$TCV_{OS}$					$\mu\text{V}/^\circ\text{C}$
AD8661		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$		3	10	$\mu\text{V}/^\circ\text{C}$
AD8662, AD8664		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$		2	9	$\mu\text{V}/^\circ\text{C}$
<b>OUTPUT CHARACTERISTICS</b>						
Output Voltage High	$V_{OH}$	$I_L = 1\text{ mA}$	4.85	4.93		$\text{V}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$	4.80			$\text{V}$
Output Voltage Low	$V_{OL}$	$I_L = 1\text{ mA}$		50	100	$\text{mV}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			110	$\text{mV}$
Short-Circuit Current	$I_{SC}$			$\pm 19$		$\text{mA}$
Closed-Loop Output Impedance	$Z_{OUT}$	$f = 1\text{ MHz}$ , $A_V = 1$		50		$\Omega$
<b>POWER SUPPLY</b>						
Supply Current per Amplifier	$I_{SY}$	$V_O = V_S/2$		1.15	1.40	$\text{mA}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			2.0	$\text{mA}$
<b>DYNAMIC PERFORMANCE</b>						
Slew Rate	SR	$R_L = 2\text{ k}\Omega$		3.5		$\text{V}/\mu\text{s}$
Gain Bandwidth Product	GBP			4		$\text{MHz}$
Phase Margin	$\Phi_O$			65		Degrees
<b>NOISE PERFORMANCE</b>						
Peak-to-Peak Noise	$e_n$ p-p	$f = 0.1\text{ Hz to }10\text{ Hz}$		2.5		$\mu\text{V p-p}$
Voltage Noise Density	$e_n$	$f = 1\text{ kHz}$		12		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		10		$\text{nV}/\sqrt{\text{Hz}}$
Current Noise Density	$i_n$	$f = 1\text{ kHz}$		0.1		$\text{pA}/\sqrt{\text{Hz}}$

## AD8661/AD8662/AD8664 ELECTRICAL CHARACTERISTICS—SOIC, MSOP, AND TSSOP

$V_S = 16.0\text{ V}$ ,  $V_{CM} = V_S/2$ ,  $T_A = 25^\circ\text{C}$ , unless otherwise noted.

Table 2.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	$V_{OS}$	$V_{CM} = V_S/2$		50	160	$\mu\text{V}$
AD8661		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			1000	$\mu\text{V}$
AD8661		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			1400	$\mu\text{V}$
AD8662		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			1000	$\mu\text{V}$
AD8664		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			1200	$\mu\text{V}$
Input Bias Current	$I_B$			0.3	1	$\text{pA}$
		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			50	$\text{pA}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			300	$\text{pA}$
Input Offset Current	$I_{OS}$			0.2	0.5	$\text{pA}$
		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			20	$\text{pA}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			75	$\text{pA}$
Input Voltage Range			-0.1		+14.0	$\text{V}$
Common-Mode Rejection Ratio	CMRR	$V_{CM} = -0.1\text{ V to }+14.0\text{ V}$	90	110		$\text{dB}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$	90	110		$\text{dB}$
Large Signal Voltage Gain	$A_{VO}$	$R_L = 2\text{ k}\Omega$ , $V_O = 0.5\text{ V to }15.5\text{ V}$	200	360		$\text{V/mV}$
Offset Voltage Drift	$TCV_{OS}$					
AD8661		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$		3	10	$\mu\text{V}/^\circ\text{C}$
AD8662, AD8664		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$		2	9	$\mu\text{V}/^\circ\text{C}$
OUTPUT CHARACTERISTICS						
Output Voltage High	$V_{OH}$	$I_L = 1\text{ mA}$	15.93	15.97		$\text{V}$
		$I_L = 10\text{ mA}$	15.60	15.70		$\text{V}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$	15.50			$\text{V}$
Output Voltage Low	$V_{OL}$	$I_L = 1\text{ mA}$		24	50	$\text{mV}$
		$I_L = 10\text{ mA}$		190	300	$\text{mV}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			350	$\text{mV}$
Short-Circuit Current	$I_{SC}$			$\pm 140$		$\text{mA}$
Closed-Loop Output Impedance	$Z_{OUT}$	$f = 1\text{ MHz}$ , $A_V = 1$		45		$\Omega$
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	$V_S = 5\text{ V to }16\text{ V}$	95	110		$\text{dB}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$	95	115		$\text{dB}$
Supply Current per Amplifier	$I_{SY}$	$V_O = V_S/2$		1.25	1.55	$\text{mA}$
		$-40^\circ\text{C} < T_A < +125^\circ\text{C}$			2.1	$\text{mA}$
DYNAMIC PERFORMANCE						
Slew Rate	SR	$R_L = 2\text{ k}\Omega$		3.5		$\text{V}/\mu\text{s}$
Gain Bandwidth Product	GBP			4		$\text{MHz}$
Phase Margin	$\Phi_O$			65		Degrees
NOISE PERFORMANCE						
Peak-to-Peak Noise	$e_n\text{ p-p}$	$f = 0.1\text{ Hz to }10\text{ Hz}$		2.5		$\mu\text{V p-p}$
Voltage Noise Density	$e_n$	$f = 1\text{ kHz}$		12		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		10		$\text{nV}/\sqrt{\text{Hz}}$
Current Noise Density	$i_n$	$f = 1\text{ kHz}$		0.1		$\text{pA}/\sqrt{\text{Hz}}$

**AD8661 ELECTRICAL CHARACTERISTICS—LFCSP ONLY**

$V_S = 5.0\text{ V}$ ,  $V_{CM} = V_S/2$ ,  $T_A = 25^\circ\text{C}$ , unless otherwise noted.

Table 3.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
<b>INPUT CHARACTERISTICS</b>						
Offset Voltage	$V_{OS}$	$V_{CM} = V_S/2$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$		50	300	$\mu\text{V}$
Input Bias Current	$I_B$	$-40^\circ\text{C} < T_A < +85^\circ\text{C}$		0.3	1	$\text{pA}$
Input Offset Current	$I_{OS}$	$-40^\circ\text{C} < T_A < +85^\circ\text{C}$		0.2	0.5	$\text{pA}$
Input Voltage Range		$-40^\circ\text{C} < T_A < +85^\circ\text{C}$			20	$\text{pA}$
Common-Mode Rejection Ratio	CMRR	$V_{CM} = -0.1\text{ V to }+3.0\text{ V}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$	-0.1	85	100	$\text{dB}$
Large Signal Voltage Gain	$A_{VO}$	$R_L = 2\text{ k}\Omega$ , $V_O = 0.5\text{ V to }4.5\text{ V}$	80	100		$\text{dB}$
Offset Voltage Drift	$TCV_{OS}$	$-40^\circ\text{C} < T_A < +85^\circ\text{C}$	100	240	17	$\text{V/mV}$ $\mu\text{V}/^\circ\text{C}$
<b>OUTPUT CHARACTERISTICS</b>						
Output Voltage High	$V_{OH}$	$I_L = 1\text{ mA}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$	4.85	4.93		$\text{V}$
Output Voltage Low	$V_{OL}$	$I_L = 1\text{ mA}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$	4.80	50	100	$\text{V}$ $\text{mV}$
Short-Circuit Current	$I_{SC}$			$\pm 19$	120	$\text{mV}$ $\text{mA}$
Closed-Loop Output Impedance	$Z_{OUT}$	$f = 1\text{ MHz}$ , $A_V = 1$		65		$\Omega$
<b>POWER SUPPLY</b>						
Supply Current per Amplifier	$I_{SY}$	$V_O = V_S/2$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$		1.15	1.40	$\text{mA}$
					1.8	$\text{mA}$
<b>DYNAMIC PERFORMANCE</b>						
Slew Rate	SR	$R_L = 2\text{ k}\Omega$		3.5		$\text{V}/\mu\text{s}$
Gain Bandwidth Product	GBP			4		$\text{MHz}$
Phase Margin	$\Phi_O$			65		Degrees
<b>NOISE PERFORMANCE</b>						
Peak-to-Peak Noise	$e_n\text{ p-p}$	$f = 0.1\text{ Hz to }10\text{ Hz}$		2.5		$\mu\text{V p-p}$
Voltage Noise Density	$e_n$	$f = 1\text{ kHz}$		12		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		10		$\text{nV}/\sqrt{\text{Hz}}$
Current Noise Density	$i_n$	$f = 1\text{ kHz}$		0.1		$\text{pA}/\sqrt{\text{Hz}}$

**AD8661 ELECTRICAL CHARACTERISTICS—LFCSP ONLY**

$V_S = 16.0\text{ V}$ ,  $V_{CM} = V_S/2$ ,  $T_A = 25^\circ\text{C}$ , unless otherwise noted.

Table 4.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
<b>INPUT CHARACTERISTICS</b>						
Offset Voltage	$V_{OS}$	$V_{CM} = V_S/2$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$		50	300	$\mu\text{V}$
Input Bias Current	$I_B$	$-40^\circ\text{C} < T_A < +85^\circ\text{C}$		0.3	1	$\mu\text{A}$
Input Offset Current	$I_{OS}$	$-40^\circ\text{C} < T_A < +85^\circ\text{C}$		0.2	0.5	$\mu\text{A}$
Input Voltage Range			-0.1		+14.0	V
Common-Mode Rejection Ratio	CMRR	$V_{CM} = -0.1\text{ V to }+14.0\text{ V}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$	90	110		dB
Large Signal Voltage Gain	$A_{VO}$	$R_L = 2\text{ k}\Omega$ , $V_O = 0.5\text{ V to }15.5\text{ V}$	200	420		V/mV
Offset Voltage Drift	$TCV_{OS}$	$-40^\circ\text{C} < T_A < +85^\circ\text{C}$		4	17	$\mu\text{V}/^\circ\text{C}$
<b>OUTPUT CHARACTERISTICS</b>						
Output Voltage High	$V_{OH}$	$I_L = 1\text{ mA}$ $I_L = 10\text{ mA}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$	15.95 15.60 15.50	15.97 15.70		V V V
Output Voltage Low	$V_{OL}$	$I_L = 1\text{ mA}$ $I_L = 10\text{ mA}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$		24 210	50 350	mV mV mV
Short-Circuit Current	$I_{SC}$			$\pm 140$		mA
Closed-Loop Output Impedance	$Z_{OUT}$	$f = 1\text{ MHz}$ , $A_V = 1$		45		$\Omega$
<b>POWER SUPPLY</b>						
Power Supply Rejection Ratio	PSRR	$V_S = 5\text{ V to }16\text{ V}$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$	95 95	110 115		dB dB
Supply Current per Amplifier	$I_{SY}$	$V_O = V_S/2$ $-40^\circ\text{C} < T_A < +85^\circ\text{C}$		1.25	1.55 1.9	mA mA
<b>DYNAMIC PERFORMANCE</b>						
Slew Rate	SR	$R_L = 2\text{ k}\Omega$		3.5		V/ $\mu\text{s}$
Gain Bandwidth Product	GBP			4		MHz
Phase Margin	$\Phi_O$			65		Degrees
<b>NOISE PERFORMANCE</b>						
Peak-to-Peak Noise	$e_n\text{ p-p}$	$f = 0.1\text{ Hz to }10\text{ Hz}$		2.5		$\mu\text{V p-p}$
Voltage Noise Density	$e_n$	$f = 1\text{ kHz}$ $f = 10\text{ kHz}$		12 10		nV/ $\sqrt{\text{Hz}}$ nV/ $\sqrt{\text{Hz}}$
Current Noise Density	$i_n$	$f = 1\text{ kHz}$		0.1		pA/ $\sqrt{\text{Hz}}$

## ABSOLUTE MAXIMUM RATINGS

Table 5.

Parameter	Rating
Supply Voltage	18V
Input Voltage	-0.1 V to $V_S$
Differential Input Voltage	18V
Output Short-Circuit Duration to GND	Indefinite
Storage Temperature Range	-60°C to +150°C
Operating Temperature Range	
R-8, RM-8, R-14, and RU-14	-40°C to +125°C
CP-8-13	-40°C to +85°C
Junction Temperature Range	-65°C to +150°C
Lead Temperature, Soldering (60 sec)	300°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

## THERMAL RESISTANCE

$\theta_{JA}$  is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 6. Thermal Resistance

Package Type	$\theta_{JA}$	$\theta_{JC}$	Unit
8-Lead SOIC	121	43	°C/W
8-Lead LFCSP	75 <sup>1</sup>	18 <sup>1</sup>	°C/W
8-Lead MSOP	142	44	°C/W
14-Lead SOIC	88.2	56.3	°C/W
14-Lead TSSOP	114	23.3	°C/W

<sup>1</sup> Exposed pad soldered to application board.

## ESD CAUTION



**ESD (electrostatic discharge) sensitive device.** Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TYPICAL PERFORMANCE CHARACTERISTICS

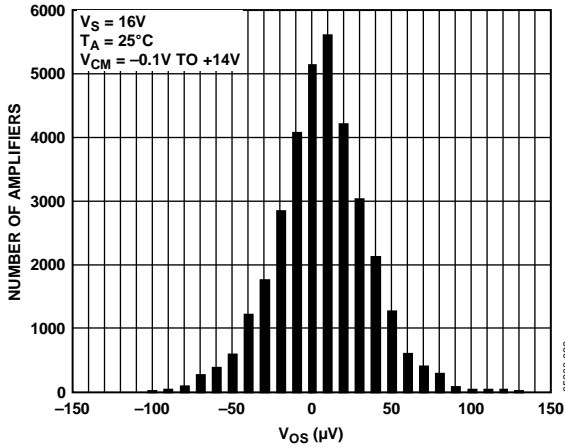


Figure 7. Input Offset Voltage Distribution

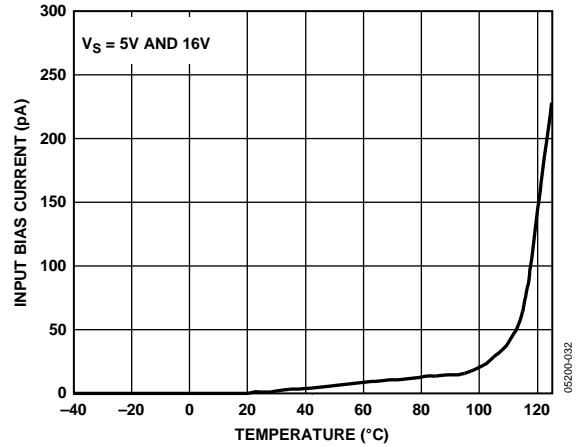


Figure 10. Input Bias Current vs. Temperature

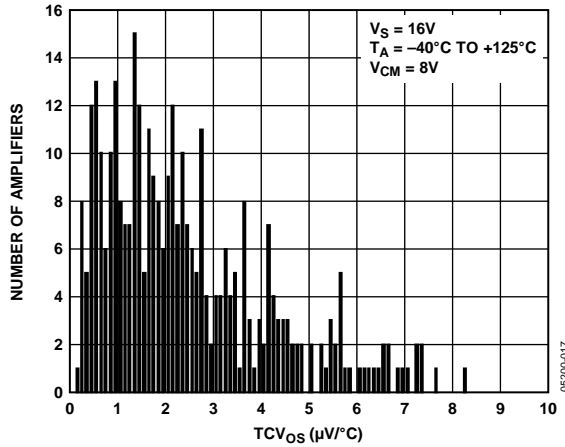


Figure 8. Offset Voltage Drift Distribution

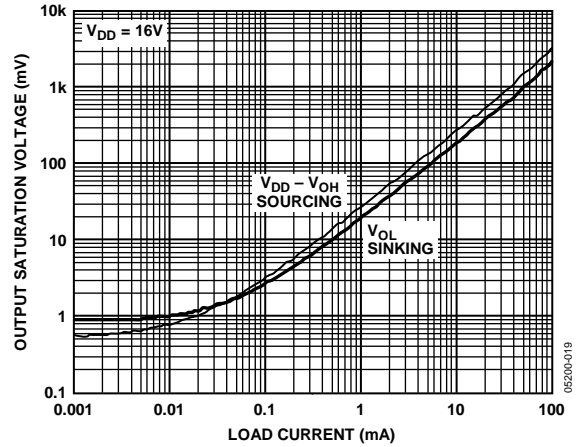


Figure 11. Output Swing Saturation Voltage vs. Load Current

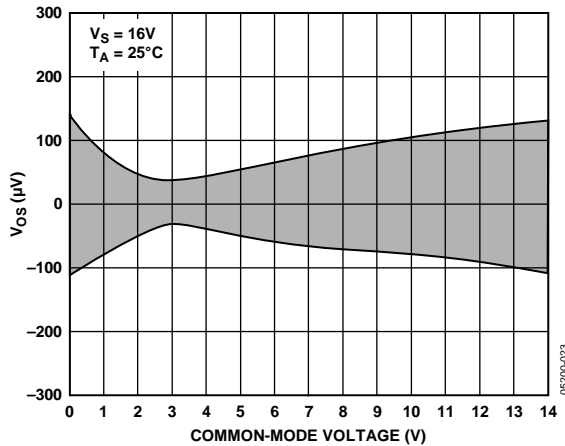


Figure 9. Input Offset Voltage vs. Common-Mode Voltage

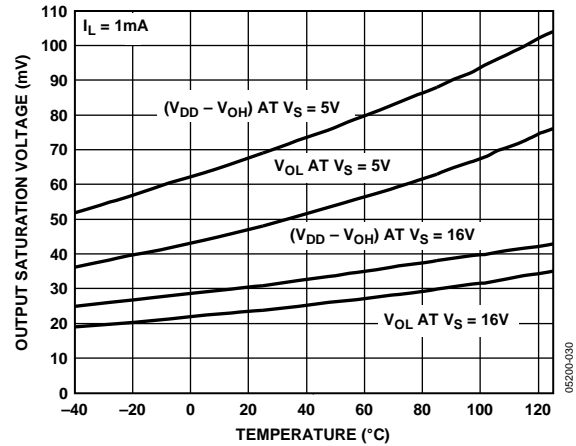


Figure 12. Output Swing Saturation Voltage vs. Temperature,  $I_L = 1 \text{ mA}$





Figure 13. Output Swing Saturation Voltage vs. Temperature,  $I_L = 10\text{ mA}$



Figure 16. CMRR vs. Frequency



Figure 14. Open-Loop Gain and Phase Shift vs. Frequency



Figure 17. PSRR vs. Frequency



Figure 15. Closed-Loop Output Impedance vs. Frequency



Figure 18. Small Signal Overshoot vs. Load Capacitance



Figure 19. Supply Current vs. Temperature



Figure 22. Small Signal Transient Response



Figure 20. Supply Current vs. Supply Voltage (Dual-Supply Configuration),  $T_A = 25^\circ\text{C}$



Figure 23. Large Signal Transient Response



Figure 21. 0.1 Hz to 10 Hz Input Voltage Noise



Figure 24. Positive Overload Recovery



Figure 25. Negative Overload Recovery

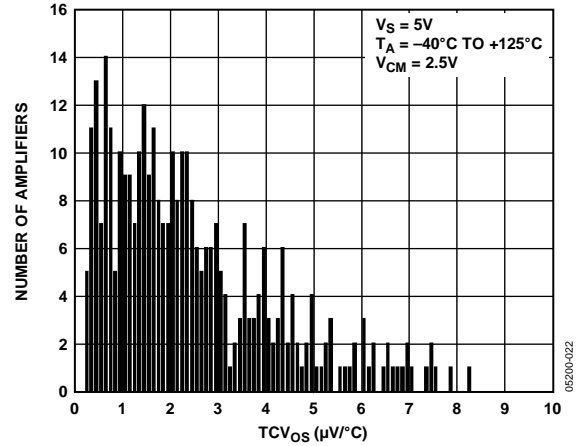


Figure 28. Offset Voltage Drift Distribution



Figure 26. Voltage Noise Density vs. Frequency

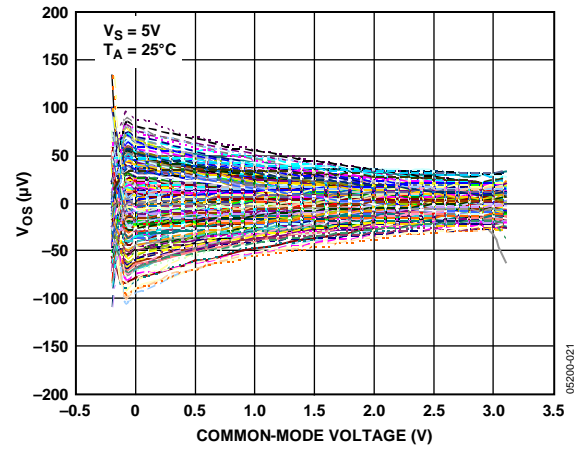


Figure 29. Input Offset Voltage vs. Common-Mode Voltage



Figure 27. Input Offset Voltage Distribution

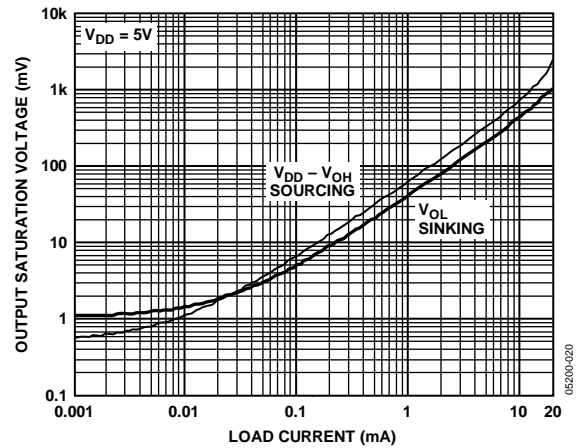


Figure 30. Output Swing Saturation Voltage vs. Load Current



Figure 31. Closed-Loop Output Impedance vs. Frequency

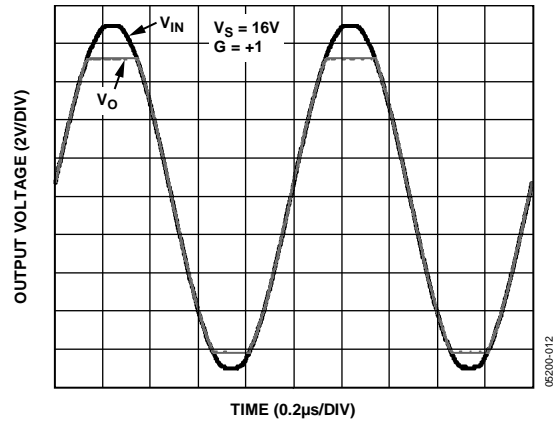
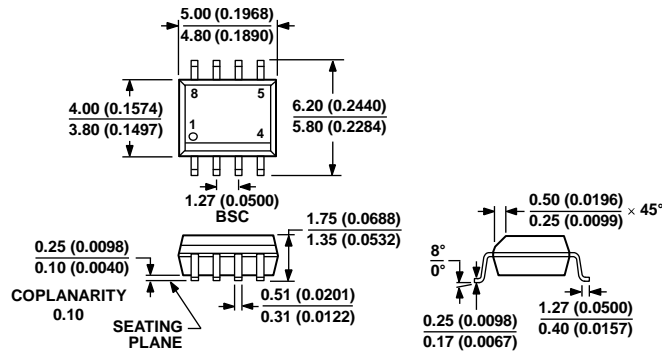


Figure 33. No Phase Reversal



Figure 32. Large Signal Transient Response

OUTLINE DIMENSIONS

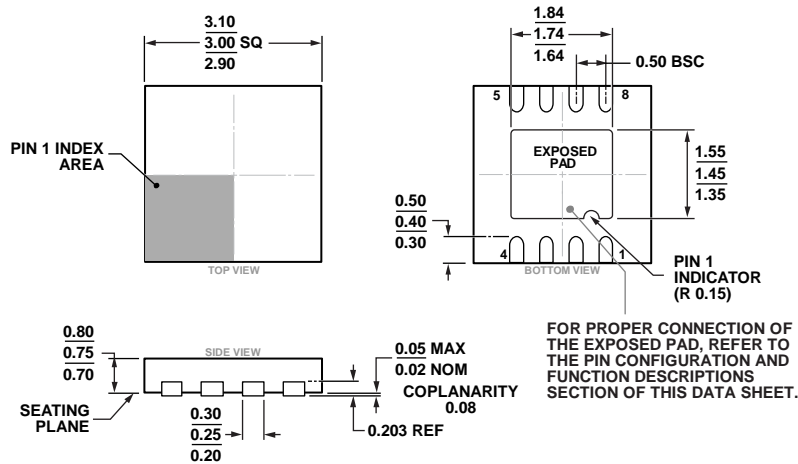


COMPLIANT TO JEDEC STANDARDS MS-012-A  
 CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS  
 (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR  
 REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

060506-A

Figure 34. 8-Lead Small Outline Package [SOIC\_N]  
 Narrow Body  
 (R-8)

Dimensions shown in millimeters and (inches)



FOR PROPER CONNECTION OF  
 THE EXPOSED PAD, REFER TO  
 THE PIN CONFIGURATION AND  
 FUNCTION DESCRIPTIONS  
 SECTION OF THIS DATA SHEET.

COMPLIANT TO JEDEC STANDARDS MO-229-WEED-4

Figure 35. 8-Lead Lead Frame Chip Scale Package [LFCSP]  
 3 mm x 3 mm Body and 0.75 mm Package Height  
 (CP-8-13)

Dimensions shown in millimeters

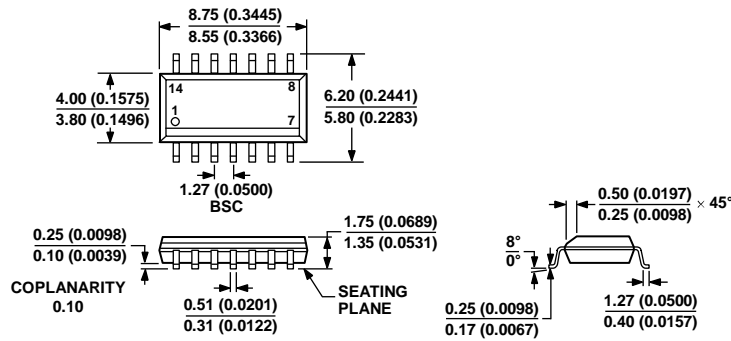
05-11-2016-A



COMPLIANT TO JEDEC STANDARDS MO-187-AA

Figure 36. 8-Lead Mini Small Outline Package [MSOP] (RM-8)

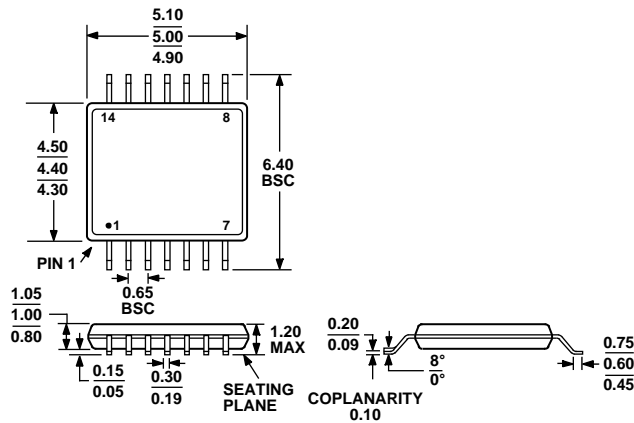
Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MS-012-AB  
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 37. 14-Lead Standard Small Outline Package [SOIC\_N] Narrow Body (R-14)

Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MO-153-AB-1

Figure 38. 14-Lead Thin Shrink Small Outline Package [TSSOP] (RU-14)

Dimensions shown in millimeters

## ORDERING GUIDE

Model <sup>1</sup>	Temperature Range	Package Description	Package Option	Branding
AD8661ARZ	−40°C to +125°C	8-Lead Small Outline Package [SOIC_N]	R-8	
AD8661ARZ-REEL	−40°C to +125°C	8-Lead Small Outline Package [SOIC_N]	R-8	
AD8661ARZ-REEL7	−40°C to +125°C	8-Lead Small Outline Package [SOIC_N]	R-8	
AD8661ACPZ-R2	−40°C to +85°C	8-Lead Lead Frame Chip Scale Package [LFCSP]	CP-8-13	AOM
AD8661ACPZ-REEL7	−40°C to +85°C	8-Lead Lead Frame Chip Scale Package [LFCSP]	CP-8-13	AOM
AD8662ARZ	−40°C to +125°C	8-Lead Small Outline Package [SOIC_N]	R-8	
AD8662ARZ-REEL	−40°C to +125°C	8-Lead Small Outline Package [SOIC_N]	R-8	
AD8662ARZ-REEL7	−40°C to +125°C	8-Lead Small Outline Package [SOIC_N]	R-8	
AD8662ARMZ	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	A10
AD8662ARMZ-REEL	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	A10
AD8664ARZ	−40°C to +125°C	14-Lead Standard Small Outline Package [SOIC_N]	R-14	
AD8664ARZ-REEL	−40°C to +125°C	14-Lead Standard Small Outline Package [SOIC_N]	R-14	
AD8664ARZ-REEL7	−40°C to +125°C	14-Lead Standard Small Outline Package [SOIC_N]	R-14	
AD8664ARUZ	−40°C to +125°C	14-Lead Thin Shrink Small Outline Package [TSSOP]	RU-14	
AD8664ARUZ-REEL	−40°C to +125°C	14-Lead Thin Shrink Small Outline Package [TSSOP]	RU-14	

<sup>1</sup> Z = RoHS Compliant Part.

**NOTES**



Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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